

MATERIAL DECLARATION



Material Number	CRL0603-FW-1R00ELF			
Product Line	Low Ohmic Chip Resistors			
Compliance Date	2018/08/14			
RoHS Compliant	YES	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic Substrate	Ceramic	1.7154	Aluminum oxide	1344-28-1	96.0%	70.26	73.19
				Silicon dioxide	14808-60-7	4.0%	2.93	
2	Conductor Layer	SILVER	0.0834	Silver	7440-22-4	95.0%	3.38	3.56
				Glass	65997-17-3	5%	0.18	
3	Resistive Element	Resistive Element	0.0827	Manganese	7439-96-5	10%	0.35	3.53
				Copper	7440-50-8	60%	2.12	
				Nickel	7440-02-0	30%	1.06	
4	Over-Coating	Epoxy	0.0877	Epoxy	25068-38-6	100%	3.74	3.74
5	Marking	Epoxy	0.0138	Epoxy	25085-99-8	100%	0.59	0.59
6	End Terminal	Nickel Chromium	0.0059	Nickel	7440-02-0	80%	0.20	0.25
				Chromium	7440-47-3	20%	0.05	
7	Plating Layer	Copper	0.1884	Copper	7440-50-8	100%	8.04	8.04
		Nickel	0.0832	Nickel	7440-02-0	100%	3.55	3.55
		Tin	0.0832	Tin	7440-31-5	100%	3.55	3.55
			Total weight	2.3438				

This Document was updated on: 9-4-2018

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.